

L Number	Hits	Search Text	DB	Time stamp
2	0	((photoinitiator or photopolymer or photopolymerizable) near (electrode or pad or terminal)) and (chip or die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/24 14:30
1	21	(photoinitiator or photopolymer or photopolymerizable) near (electrode or pad or terminal)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/24 14:35
3	14	257/778.cccls. and (photoinitiator or photopolymer or photopolymerizable)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/24 17:19
4	1	6331736.URPN.	USPAT	2003/06/24 14:49
5	28	("3461357" "3809625" "3881971" "4808552" "4988423" "5106461" "5130768" "5231590" "5244837" "5341310" "5414637" "5495397" "5506172" "5523253" "5523626" "5534465" "5570504" "5597470" "5619017" "5632631" "5640761" "5666007" "5679609" "5688721" "5751031" "5904556" "6078100" "6175161").PN.	USPAT	2003/06/24 14:49
8	1964	((circuit adj (substrate or board)) and (photoinitiator or photopolymer or photopolymerizable))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/24 15:02
9	306	((circuit adj (substrate or board)) with (photoinitiator or photopolymer or photopolymerizable))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/24 15:05
10	293	((circuit adj (substrate or board)) with (photoinitiator or photopolymer or photopolymerizable)) and (@ad<20010718))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/24 17:43
11	34	((((circuit adj (substrate or board)) with (photoinitiator or photopolymer or photopolymerizable)) and (@ad>20010718)) and ((terminal or pad or electrode) with (photoinitiator or photopolymer or photopolymerizable)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/24 17:21
12	46	257/778.cccls. and ((resin and (pad or terminal or electrode) with ball))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/24 15:48
13	580	257/778.cccls. and (circuit adj (board or substrate)) and ball	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/24 15:50
14	160	(257/778.cccls. and (circuit adj (board or substrate)) and ball) and underfill	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/24 15:51
15	131	((257/778.cccls. and (circuit adj (board or substrate)) and ball) and underfill) and (@ad<20010718))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/24 16:34
16	1	("5903056").PN.	USPAT	2003/06/24 16:34

17	152	((bake or baking) near (photoinitiator or photopolymer or photopolymerizable or polymer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/24 17:51
18	125	((bake or baking) near (photoinitiator or photopolymer or photopolymerizable or polymer)) and (@ad<20010718)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/24 17:21
19	37	((bake or baking) near (photoinitiator or photopolymer or photopolymerizable or polymer)) and (@ad<20010718)) and (terminal or pad or electrode)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/24 17:23
20	0	((bake or baking) with (terminal or electrode or pad)) near (photoinitiator or photopolymer or photopolymerizable or polymer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/24 17:42
21	483	((bake or baking) with (terminal or electrode or pad)) and (photoinitiator or photopolymer or photopolymerizable or polymer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/24 17:43
22	171	((bake or baking) with (terminal or electrode or pad)) and (photoinitiator or photopolymer or photopolymerizable or polymer) and ((terminal or electrode or pad) with (photoinitiator or photopolymer or photopolymerizable or polymer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/24 17:43
23	143	((bake or baking) with (terminal or electrode or pad)) and (photoinitiator or photopolymer or photopolymerizable or polymer) and ((terminal or electrode or pad) with (photoinitiator or photopolymer or photopolymerizable or polymer)) and (@ad<20010718)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/24 17:44
24	20	((bake or baking) with (terminal or electrode or pad)) and (photoinitiator or photopolymer or photopolymerizable or polymer) and ((terminal or electrode or pad) with (photoinitiator or photopolymer or photopolymerizable or polymer))) and (@ad<20010718)) and ((chip or die or semiconductor) and (board or substrate))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/24 17:45
25	0	((bake or baking) and (warp or warping or bend or bending)) near (photoinitiator or photopolymer or photopolymerizable or polymer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/24 17:52
26	175	(warp or warping or bend or bending) with (photoinitiator or photopolymer or photopolymerizable or polymer) and (electrode or pad or terminal))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/24 17:53